

**PCN# 20151105001**  
**Wafer Diameter Change for Select Devices in the LBC3S Process at DL-LIN**  
**Change Notification / Sample Request**

**Date:** 11/12/2015

**To:** Digi-Key PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

**20151105001**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
SN65HVD1176D	null
SN65HVD1176DR	null
SN65HVD22D	null
SN65HVD22DR	null
SN65HVD22P	null
SN65HVD234D	null
SN65HVD234DG4	null
SN65HVD234DR	null
SN65HVD234DRG4	null
SN75HVD1176D	null
SN75HVD1176DR	null
TLC084AID	null
TLC084AIN	null
TLC085AIDR	null
TLC2252AID	null
TLC2252AIDR	null
TLC2252AIP	null
TLC2252AIPWR	null
TLC2252CD	null
TLC2252CDR	null
TLC2252CPWR	null
TLC2252ID	null
TLC2252IDR	null
TLC2254AID	null
TLC2254AIDR	null
TLC2254AIN	null
TLC2254AIPW	null
TLC2254AIPWR	null
TLC2254CD	null
TLC2254CPW	null
TLC2254CPWR	null
TLC2254ID	null
TLC2262AID	null
TLC2262AIDR	null
TLC2262AIPW	null
TLC2262AIPWR	null
TLC2262CD	null
TLC2262CDG4	null
TLC2262CDR	null
TLC2262CP	null
TLC2262CPWR	null
TLC2262ID	null
TLC2262IDR	null
TLV2252AID	null
TLV2252AIDR	null
TLV2252AIP	null
TLV2252AIPW	null
TLV2252AIPWR	null
TLV2252ID	null
TLV2252IDR	null
TLV2254AID	null
TLV2254AIN	null
TLV2254AIPW	null
TLV2254AIPWR	null

TLV2254ID	null
TLV2254IN	null
TLV2262AID	null
TLV2262AIDR	null
TLV2262AIPWR	null
TLV2262ID	null
TLV2262IPWR	null
TLV2372IDGK	null
TLV2372IDGKG4	null
TLV2372IDGKR	null
TLV2462CDGK	null
TLV2463CDGSG4	null
TLV272CDGK	null
TLV272CDGKR	null
TLV272IDGK	null
TLV272IDGKR	null
UCC27424D	null
UCC27424DGN	null
UCC27424DGNR	null
UCC27424DR	null
UCC27424P	null
TLC084AIPWP	null
TLC085AID	null
TLC085AIN	null
TLC085AIPWP	null
TLC2252CP	null
TLC2252IP	null
TLC2254CN	null
TLC2254IN	null
TLC2262AIP	null
TLC2262IP	null
TLV2252IP	null
TLV2262AIP	null
TLV2262IP	null
TLV2462IDGKR	null
TLV2463CDGS	null
TLV2463IDGSR	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20151105001	<b>PCN Date:</b>	11/12/2015
<b>Title:</b>	Wafer Diameter Change for Select Devices in the LBC3S Process at DL-LIN		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	02/12/2016	<b>Estimated Sample availability:</b>	Date Provided at Sample request

<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Process

### PCN Details

**Description of Change:**

This change notification is to announce a wafer diameter change only for select devices in the LBC3S process at DL-LIN. This is not a fab site change.

Current	New
Site/Process/Wafer Diameter	Site/Process/ <b>Wafer Diameter</b>
DL-LIN/LBC3S Process/150mm	DL-LIN/LBC3S Process/ <b>200mm</b>

The LBC3 process is a mature process which has been successfully running production since 02/2000 at DL-LIN.

**Reason for Change:**

Continuity of supply.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Changes to product identification resulting from this PCN:**

*Note: This is not a fab site change. The 6" line and 8" line are in the same location.*

Chip Site	Chip site code (20L)	Chip country code (21L)	Chip Site City
<b>DL-LIN</b>	<b>DLN</b>	<b>USA</b>	<b>Dallas</b>

**Sample Product Shipping Label (not actual product label)**

 <b>TEXAS INSTRUMENTS</b> MADE IN: Malaysia 2DC: 2Q:	 G4		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS				
<table border="1"> <tr> <td>MSL '2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table>	MSL '2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04			
MSL '2 / 260C / 1 YEAR	SEAL DT						
MSL 1 / 235C / UNLIM	03/29/04						
OPT: ITEM: 39 <b>LBL: 5A (L) T0:1750</b>							

**Product Affected:**

SN65HVD1176D	TLC2252CPWR	TLC2262CPWG4	TLV2262IDR
SN65HVD1176DG4	TLC2252CPWRG4	TLC2262CPWR	TLV2262IDRG4
SN65HVD1176DR	TLC2252ID	TLC2262CPWRG4	TLV2262IP
SN65HVD1176DRG4	TLC2252IDG4	TLC2262ID	TLV2262IPW
SN65HVD22D	TLC2252IDR	TLC2262IDG4	TLV2262IPWG4
SN65HVD22DG4	TLC2252IDRG4	TLC2262IDR	TLV2262IPWR
SN65HVD22DR	TLC2252IP	TLC2262IDRG4	TLV2262IPWRG4
SN65HVD22DRG4	TLC2254AID	TLC2262IP	TLV2372IDGK
SN65HVD22P	TLC2254AIDG4	TLV2252AID	TLV2372IDGKG4
SN65HVD22PE4	TLC2254AIDR	TLV2252AIDG4	TLV2372IDGKR
SN65HVD234D	TLC2254AIDRG4	TLV2252AIDR	TLV2372IDGKRG4
SN65HVD234DG4	TLC2254AIN	TLV2252AIDRG4	TLV2462CDGK
SN65HVD234DR	TLC2254AIPW	TLV2252AIP	TLV2462CDGKG4
SN65HVD234DRG4	TLC2254AIPWR	TLV2252AIPW	TLV2462CDGKR
SN75HVD1176D	TLC2254AIPWRG4	TLV2252AIPWG4	TLV2462CDGKRG4
SN75HVD1176DG4	TLC2254CD	TLV2252AIPWR	TLV2462IDGK
SN75HVD1176DR	TLC2254CDG4	TLV2252AIPWRG4	TLV2462IDGKG4
SN75HVD1176DRG4	TLC2254CDR	TLV2252ID	TLV2462IDGKR
TLC084AID	TLC2254CDRG4	TLV2252IDG4	TLV2462IDGKRG4
TLC084AIDG4	TLC2254CN	TLV2252IDR	TLV2463CDGS
TLC084AIDR	TLC2254CPW	TLV2252IDRG4	TLV2463CDGSG4
TLC084AIDRG4	TLC2254CPWG4	TLV2252IP	TLV2463CDGSR
TLC084AIN	TLC2254CPWR	TLV2254AID	TLV2463CDGSRG4
TLC084AIPWP	TLC2254CPWRG4	TLV2254AIDG4	TLV2463IDGS
TLC084AIPWPR	TLC2254ID	TLV2254AIDR	TLV2463IDGSG4
TLC084AIPWPRG4	TLC2254IDG4	TLV2254AIDRG4	TLV2463IDGSR
TLC085AID	TLC2254IDR	TLV2254AIN	TLV2463IDGSRG4
TLC085AIDR	TLC2254IDRG4	TLV2254AIPW	TLV272CDGK
TLC085AIN	TLC2254IN	TLV2254AIPWG4	TLV272CDGKG4
TLC085AIPWP	TLC2262AID	TLV2254AIPWR	TLV272CDGKR
TLC2252AID	TLC2262AIDG4	TLV2254AIPWRG4	TLV272CDGKRG4
TLC2252AIDG4	TLC2262AIDR	TLV2254ID	TLV272IDGK
TLC2252AIDR	TLC2262AIDRG4	TLV2254IDG4	TLV272IDGKG4
TLC2252AIDRG4	TLC2262AIP	TLV2254IDR	TLV272IDGKR
TLC2252AIP	TLC2262AIPE4	TLV2254IDRG4	TLV272IDGKRG4
TLC2252AIPE4	TLC2262AIPW	TLV2254IN	UCC27424D
TLC2252AIPW	TLC2262AIPWG4	TLV2262AID	UCC27424DG4
TLC2252AIPWR	TLC2262AIPWR	TLV2262AIDG4	UCC27424DGN
TLC2252AIPWRG4	TLC2262AIPWRG4	TLV2262AIDR	UCC27424DGNNG4
TLC2252CD	TLC2262CD	TLV2262AIDRG4	UCC27424DGNR
TLC2252CDG4	TLC2262CDG4	TLV2262AIP	UCC27424DGNRG4
TLC2252CDR	TLC2262CDR	TLV2262AIPW	UCC27424DR
TLC2252CDRG4	TLC2262CDRG4	TLV2262AIPWG4	UCC27424DRG4
TLC2252CP	TLC2262CP	TLV2262AIPWR	UCC27424P
TLC2252CPW	TLC2262CPE4	TLV2262ID	UCC27424PE4

TLC2252CPWG4	TLC2262CPW	TLV2262IDG4	
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## Qualification Report

### Conversion of select devices from 150mm wafers to 200mm wafers in DFAB

Approve Date 05-Nov-2015

#### Product Attributes

Attributes	Qual Device: SN65HVD1176 D	Qual Device: SN65HVD22 P	Qual Device: SN65HVD234 D	Qual Device: TLC085AIPWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372IDG K	Qual Device: TLV2463IDGS	Qual Device: UCC27424D	QBS Process Reference: SN104605PN
Assembly Site	FMX	FMX	FMX	TAI	FMX	FMX	-	HNT	-	FMX	TAI
Package Family	SOIC	PDIP	SOIC	HTSSOP	SOIC	PDIP	SOIC	MSOP	MSOP	SOIC	LQFP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	-
Wafer Fab Supplier	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB	DFAB
Wafer Process	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S	LBC3S

-QBS: Qual By Similarity

-Qual Devices qualified at LEVEL1-260C: SN65HVD1176D, SN65HVD234D, TLV2372IDGK, TLV2262ID, TLV2252ID, UCC27424D, TLV2463IDGS,

-Qual Devices qualified at Not Classified: SN65HVD22P, TLV2254IN

-Qual Device TLC085AIPWP is qualified at LEVEL2-260C

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN65HVD1 176D	Qual Device: SN65HVD2 2P	Qual Device: SN65HVD2 34D	Qual Device: TLC085AI PWP	Qual Device: TLV2252ID	Qual Device: TLV2254IN	Qual Device: TLV2262ID	Qual Device: TLV2372 IDGK	Qual Device: TLV2463I DGS	Qual Device: UCC274 24D	QBS Process Reference: SN104605PN
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	-	1/3/0	-	-	-	-	1/3/0	1/3/0	1/3/0	-
HBM	ESD - HBM	5000 V	-	1/3/0	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Bus & Ground pins)	10000V	1/3/0	-	-	-	-	-	-	-	-	-	-
HBM	ESD - HBM (Pin 7, 6 and gnd)	16000 V	-	1/3/0	1/3/0	-	-	-	-	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
HTOL	Life Test 155C	1000 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0
LU	Latch-up	(per JEESD78)	1/6/0	1/6/0	-	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	-
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	-	-	-	-	-	-	-	3/231/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	-

-Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

-The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

-The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

-The following are equivalent Temp Cycle options per JEESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>